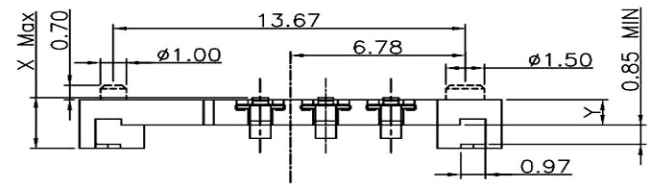
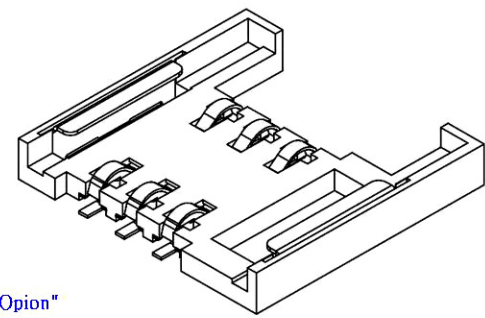


1 2 3 4 5 6 7 8

A

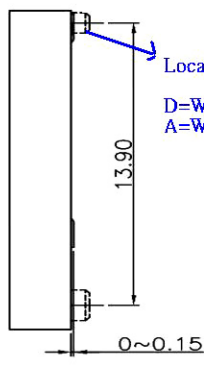
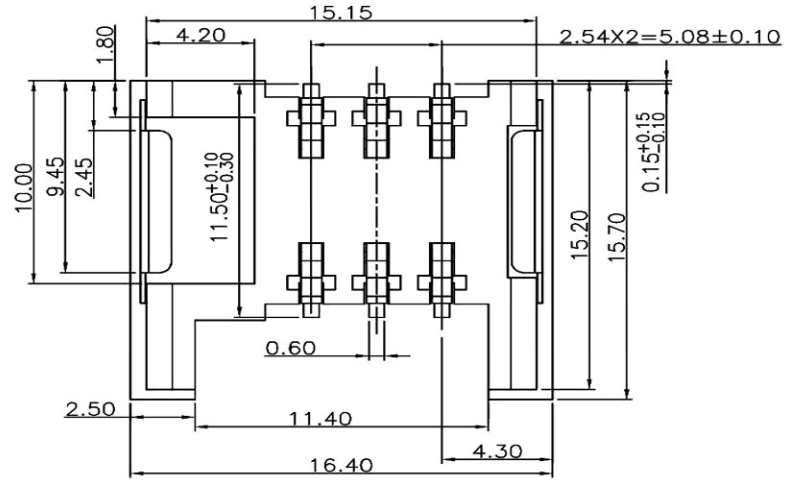


Height	
2.5	X
1.25	Y



A

B



Locating Peg "Option"
 D=W/ Locating Peg & W/O Switch
 A=W/O Locating Peg & W/O Switch

B

C

D

Material:

Housing: High Temperature Plastic UL94V-0.
 Contacts: Phosphor Bronze.
 Shell: Stainless Steel , Tin Plated All Over.

C

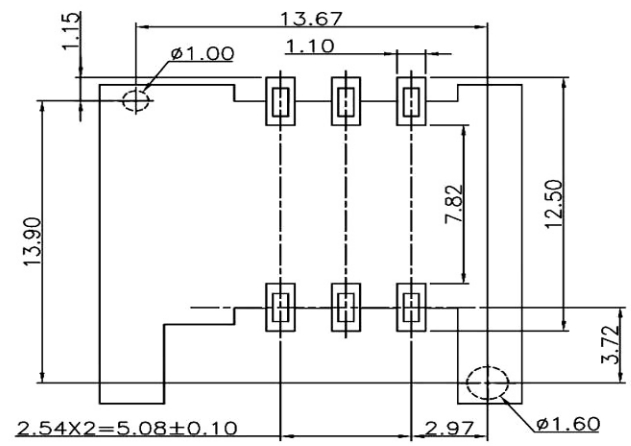
E

Electrical Characteristics:

Current Rating: 1 AMP.
 Dielectric Withstanding Voltage: AC 500V For 1 minute.
 Insulator Resistance: 1000MΩ min. at DC 500V.
 Contact Resistance: 100mΩ max. at DC 100mA.
 Operating Temperature: -40°C ~+85°C .

D

F



P.C. Board Layout
 (Tolerance: ±0.05)

E

G

RoHS Compliant		HSM 玄茂科技股份有限公司 HSUAN MAO TECHNOLOGY CO., LTD.	
APPD. 核准	SCALE 比例	TOLERANCE 零件公差	PART NAME 品名
DWG. 製圖	UNIT 單位	SIZE 板張尺寸	SIM CARD SLIDE IN TYPE 6PIN SMT 90° ROW PITCH=10.16MM H=2.5MM (W/ LOCATING PEG OR W/O LOCATING) & W/O SWITCH TUBE ROHS
DATE 制表日	PAGE 張數	REV. 版本	PART NO. 料號
2012/6/22	1 OF 1	B	C0610-06BC(D,A)XBXR

G

H

1 2 3 4 5 6 7 8